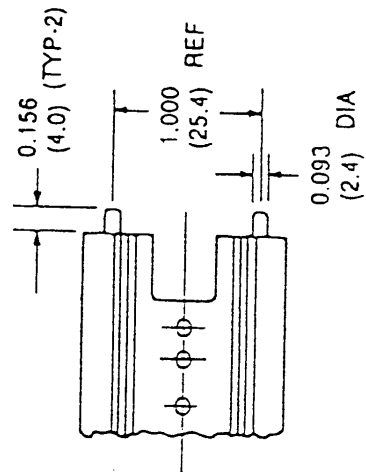
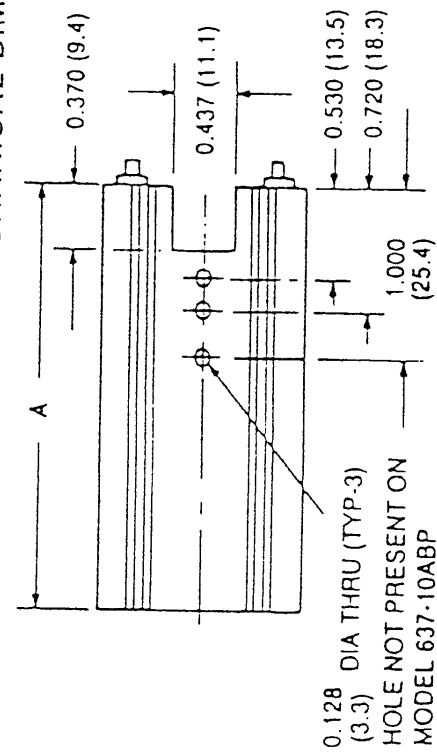
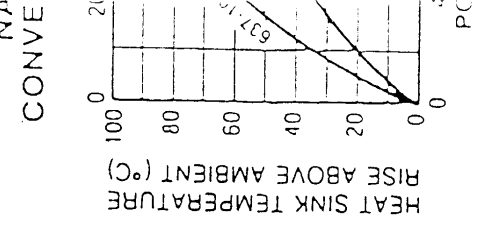


Wave-solderable pins on 1 in. centers for vertical mounting on printed circuit boards. Maximum semiconductor heat sink where weight and board space occupied must be minimized. Refer to the Accessory Products thermal compounds, and other accessories products. Material: aluminum, black anodized.

MECHANICAL DIMENSIONS



637 SERIES
(EXTRUSION PROFILE 5183)



637 SERIES

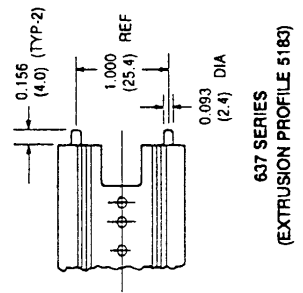
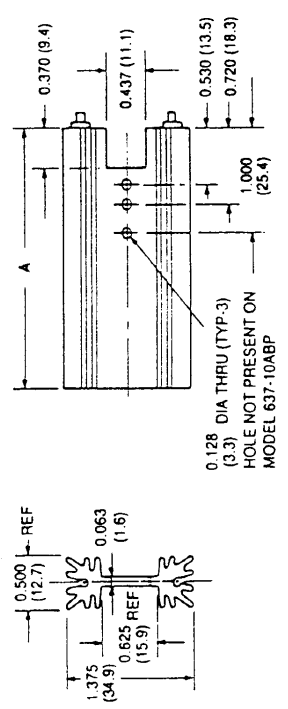
Standard P/N	Height Above PC Board "A"	Maximum Footprint
637-10ABP ▲	1.000 in. (25.4)	1.375 in. (34.9) x 0.500 (12.7)
637-15ABP ▲	1.500 in. (38.1)	1.375 in. (34.9) x 0.500 (12.7)
637-20ABP ▲	2.000 in. (50.8)	1.375 in. (34.9) x 0.500 (12.7)
637-25ABP ▲	2.500 in. (63.5)	1.375 in. (34.9) x 0.500 (12.7)

High-Efficiency Heat Sinks for Vertical Board Mounting

Thermal Performance at Typical Load		Weight
Natural Convection	76°C @ 6W	lbs (grams)
Forced Convection	65°C @ 6W	0.023 (10.43)
	55°C @ 6W	0.035 (15.88)
	48°C @ 6W	0.050 (22.68)
		0.062 (28.12)

Wave-solderable pins on 1 in. centers for vertical mounting on printed circuit boards. Maximum semiconductor package width 0.625 in. (15.9). Use this heat sink where weight and board space occupied must be minimized. Refer to the Accessory Products section for thermal interface materials, thermal compounds, and other accessories products. Material: aluminum, black anodized.

MECHANICAL DIMENSIONS



637 SERIES
(EXTRUSION PROFILE 5183)

